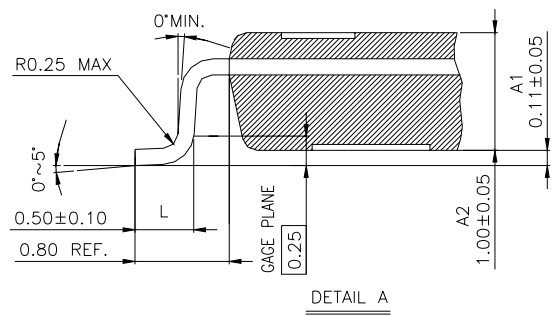
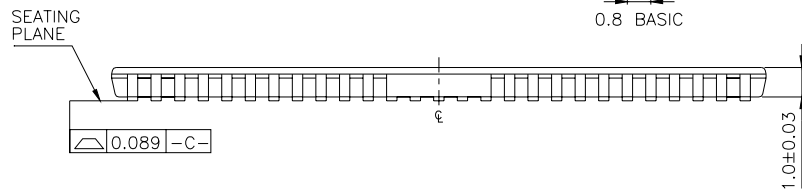
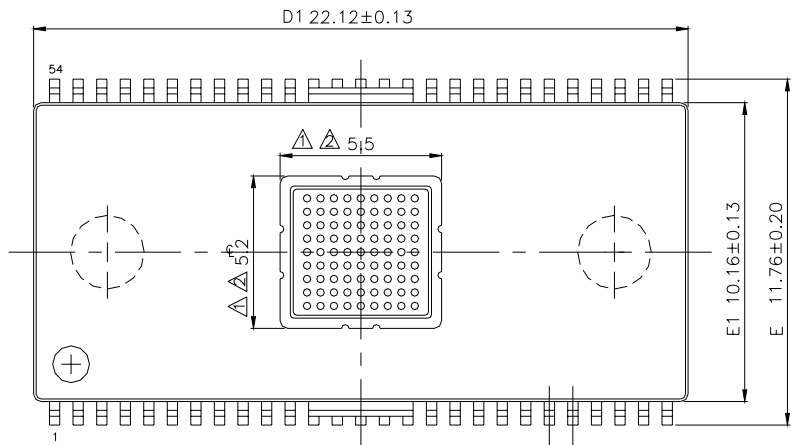
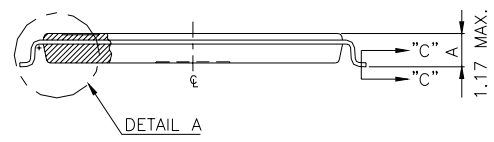


- NOTES:
1. ALL DIMENSIONS ARE IN MM.
 2. DIMENSION D1 AND E1 DOES NOT INCLUDE MOLD PROTRUSION.
 3. COPLANARITY OF ALL LEADS SHALL BE 3.5 MILS MAX. (BEFORE TEST) UNLESS OTHERWISE SPECIFIED.
 4. GENERAL PHYSICAL OUTLINE SPEC IS REFER TO TMC'S FINAL VISUAL INSPECTION SPEC UNLESS OTHERWISE SPECIFIED.
 5. PLATING THICKNESS 0.200~0.800 MILS.

3			
2			
1	修改圖形		<i>Jim Hu</i> 930309
REV.	DESCRIPTION OF REVISION		SIGNATURE/ DATE
晶揚科技股份有限公司 Taiwan Micropaq Corporation		HTSOP 54 CU L/F PACKAGE OUTLINE DWG.	
DWG. NO. EOL-S0540400-003 R1		FILE S54400003	
DESIGNER	DATE	MATERIAL	SCALE
<i>Jim Hu</i>	930309		5:1
CHECKER	DATE	PROCESSES	SHEET NO.
			1 OF 1
APPROVED	DATE	UNIT	
		MM	
			.XXXX ±.0005 .XXX ±.0025 .XX ±.0100 .X ±.0250 ALL DIMENSIONS IN MILLIMETERS.



- NOTES:
1. ALL DIMENSIONS ARE IN MM.
 2. DIMENSION D1 AND E1 DOES NOT INCLUDE MOLD PROTRUSION.
 3. COPLANARITY OF ALL LEADS SHALL BE 3.5 MILS MAX. (BEFORE TEST) UNLESS OTHERWISE SPECIFIED.
 4. GENERAL PHYSICAL OUTLINE SPEC IS REFER TO TMC'S FINAL VISUAL INSPECTION SPEC UNLESS OTHERWISE SPECIFIED.
 5. PLATING THICKNESS 0.200~0.800 MILS.



3				
2	修改圖形			<i>for the 20007</i>
1	增加尺寸標示			<i>Shy Shany 20007</i>
REV.	DESCRIPTION OF REVISION			SIGNATURE/DATE
晶揚科技股份有限公司 <i>Taiwan Micropaq Corporation</i>			TITLE HTSOP 54 CU-FS L/F PACKAGE OUTLINE DWG.	
DWG. NO. EOL-S0540400-002 R2			FILE S54400002	
DESIGNER	DATE	MATERIAL	SCALE	.XXXX ±.0005 .XXX ±.0025 .XX ±.0100 .X ±.0250 ALL DIMENSIONS IN MILLIMETERS.
<i>for the 20007</i>	<i>20007</i>		5:1	
CHECKER	DATE	PROCESSES	SHEET NO. 1 OF 1	
APPROVED	DATE	UNIT MM		